

ABSTRACT OF THE DISCLOSURE

Multiple through holes in a printed circuit board (PCB) are filled with a malleable, electrically conductive material, such as an elastomer containing a concentration of conductive particles. The material in each through hole forms an electrical contact at which a solder ball or pin of a ball grid array (BGA) or pin grid array (PGA) of a microelectronic package, respectively, will be coupled to the PCB.

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